Datasheet

Sound Processor with Built-in 3-band Equalizer

BD37544FS

General Description

BD37544FS is a sound processor with built-in 3-band equalizer for car audio. The functions are stereo input selector (which can switch single and GND isolation), input-gain control, main volume, super bass, 5ch fader volume, LPF/HPF for subwoofer, and mixing input. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and can construct a high quality car audio system.

Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, super bass, mixing by using advanced switch circuit.
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces switching noise for volume of a portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer, and HPF. It is possible to control Q, G_V, f_O of 3-band equalizer and f_C of LPF/HPF through I^2C BUS control.
- It is possible to adjust the gain of the bass, middle, and treble up to ±20dB with 1 dB step gain adjustment.
- It is equipped with output terminals for Subwoofer. Moreover, the stereo signal output of the front and rear can also be chosen by the I^2C BUS control.
- Built-in mixing input and mixing attenuator.
- Energy-saving design resulting in low-current consumption is achieved by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB layout.
- It is possible to control the I^2C BUS by 3.3V / 5V.

Applications

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

Key Specifications

■ Power Supply Voltage Range:	7.0V to 9.5V
■ Circuit Current (No Signal):	38mA (Typ)
■ Total Harmonic Distortion:	
THD+N1	0.001% (Typ)
THD+N2	0.002% (Typ)
■ Maximum Input Voltage:	2.3Vrms(Typ)
■ Cross-talk Between Selectors:	-100dB(Typ)
■ Volume Control Range:	+15 dB to -79dB
■ Output Noise Voltage:	
V_{NO1}	3.8µVrms(Typ)
V_{NO2}	4.8µVrms(Typ)
■ Residual Output Noise Voltage:	1.8µVrms(Typ)
■ Operating Temperature Range:	-40°C to +85°C

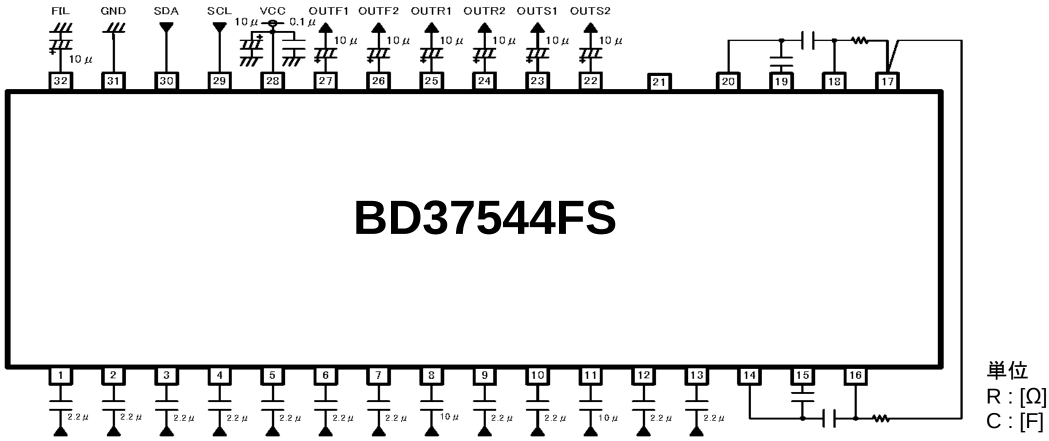
Package

W(Typ) x D(Typ) x H(Max)

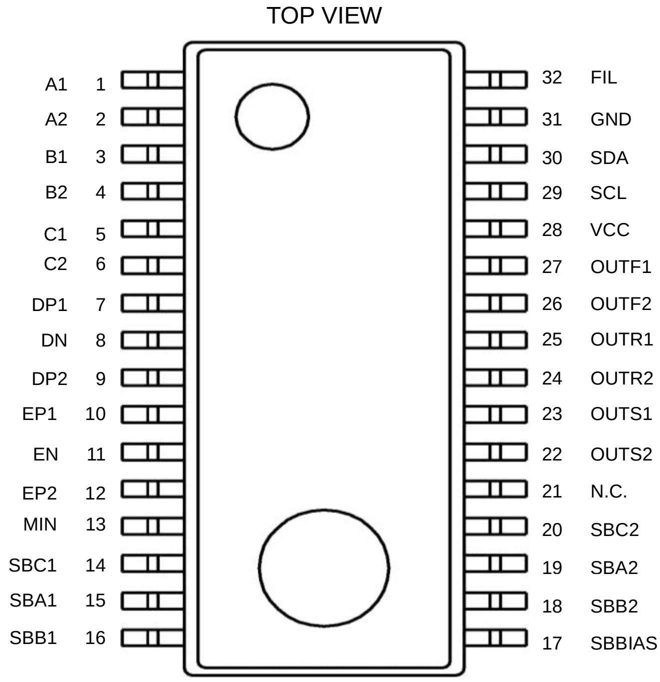
SSOP-A32
13.60 mm x 7.80mm x 2.01mm

○Product structure : Silicon monolithic integrated circuit ○This product has no designed protection against radioactive rays

Typical Application Circuit



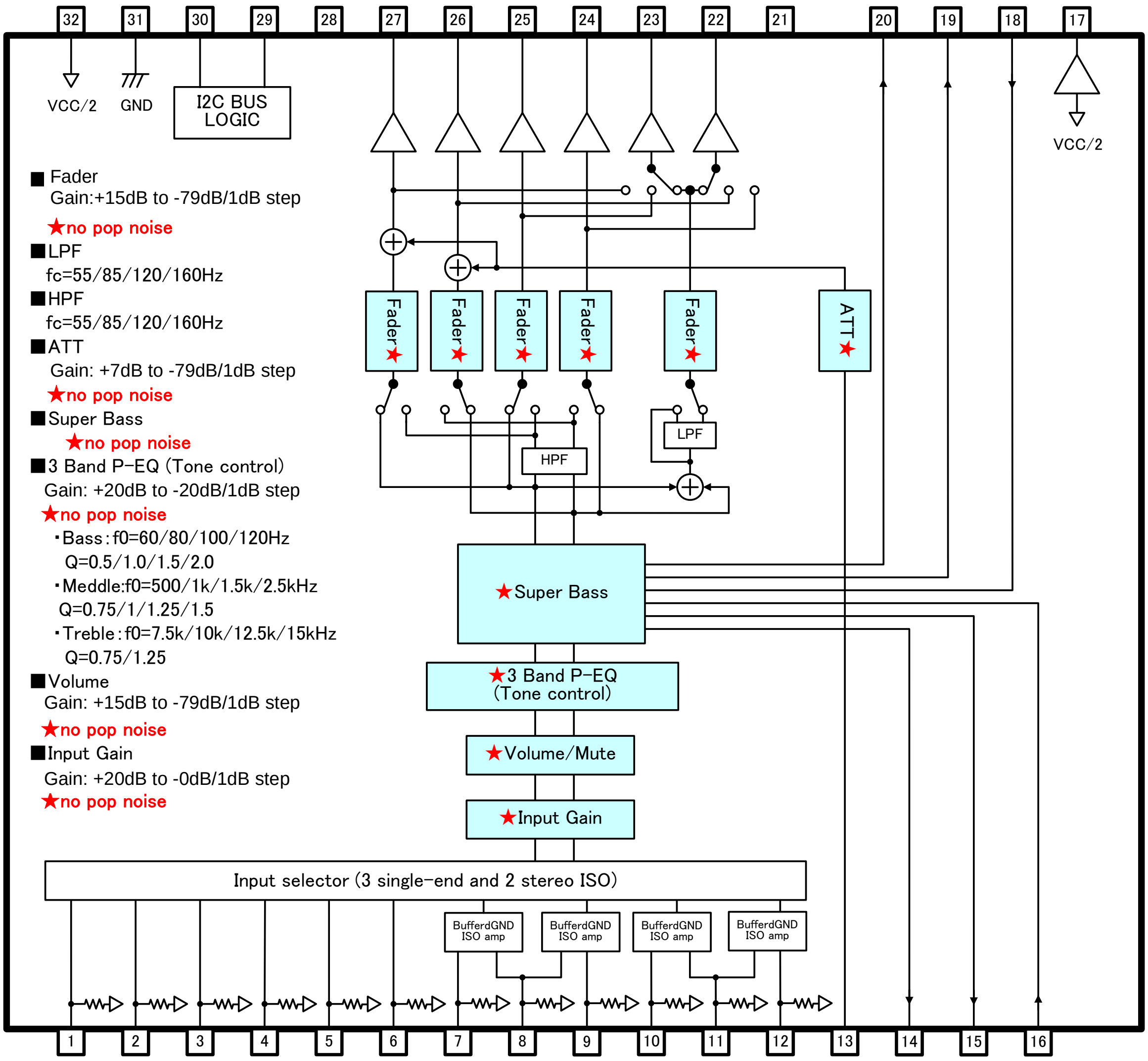
Pin Configuration



Pin Descriptions

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	17	SBBIAS	SuperBass bias terminal
2	A2	A input terminal of 2ch	18	SBB2	SuperBass setting terminal of 2ch
3	B1	B input terminal of 1ch	19	SBA2	SuperBass setting terminal of 2ch
4	B2	B input terminal of 2ch	20	SBC2	SuperBass setting terminal of 2ch
5	C1	C input terminal of 1ch	21	N.C.	No connection
6	C2	C input terminal of 2ch	22	OUTS2	Subwoofer output terminal of 2ch
7	DP1	D positive input terminal of 1ch	23	OUTS1	Subwoofer output terminal of 1ch
8	DN	D negative input terminal	24	OUTR2	Rear output terminal of 2ch
9	DP2	D positive input terminal of 2ch	25	OUTR1	Rear output terminal of 1ch
10	EP1	E positive input terminal of 1ch	26	OUTF2	Front output terminal of 2ch
11	EN	E negative input terminal	27	OUTF1	Front output terminal of 1ch
12	EP2	E positive input terminal of 2ch	28	VCC	Power supply terminal
13	MIN	Mixing input terminal	29	SCL	I^2C Communication clock terminal
14	SBC1	SuperBass setting terminal of 1ch	30	SDA	I^2C Communication data terminal
15	SBA1	SuperBass setting terminal of 1ch	31	GND	GND terminal
16	SBB1	SuperBass setting terminal of 1ch	32	FIL	VCC/2 terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	V_{CC}	10.0	V
Input Voltage	V_{IN}	V_{CC}+0.3 to GND-0.3	V
Power Dissipation	Pd	0.95 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on the standard board (70 x 70 x 1.6 mm^3), derate by 7.6mW/°C for Ta above 25°C.
Thermal resistance θja = 131.6(°C/W)
Material : A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Power Supply Voltage	V_{CC}	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

Electrical Characteristics

(Unless specified, Ta=25°C, V_{CC}=8.5V, f=1kHz, V_{IN}=1Vrms, Rg=600Ω, R_L=10kΩ, A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, HPF OFF, Mixing OFF, Fader 0dB)

BLOCK	Parameter	Symbol	Limit			Unit	Conditions
			Min	Typ	Max		
GENERAL	Circuit Current (No Signal)	I_Q	-	38	48	mA	No signal
	Voltage Gain	G_V	-1.5	0	+1.5	dB	G_V=20log(V_{OUT}/V_{IN})
	Channel Balance	CB	-1.5	0	+1.5	dB	CB = G_{V1}-G_{V2}
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V_{OUT}=1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V_{OUT}=1Vrms BW=400Hz-30KHz
	Output Noise Voltage 1 (FRONT,REAR) *	V_{NO1}	-	3.8	15	μVrms	Rg = 0Ω BW = IHF-A
	Output Noise Voltage 2 (SUBWOOFER) *	V_{NO2}	-	4.8	15	μVrms	Rg = 0Ω BW = IHF-A
	Residual Output Noise Voltage*	V_{NOR}	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Cross-talk Between Channels *	CTC	-	-100	-90	dB	Rg = 0Ω CTC=20log(V_{OUT}/V_{IN}) BW = IHF-A
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V_{RR}=100mVrms RR=20log(V_{CC} IN/V_{OUT})
INPUT SELECTOR	Input Impedance(A, B,C)	R_{IN_S}	70	100	130	kΩ	
	Input Impedance(D, E)	R_{IN_D}	175	250	325	kΩ	
	Maximum Input Voltage	V_{IM}	2.1	2.3	-	Vrms	V_{IM} at THD+N(V_{OUT})=1% BW=400Hz-30KHz
	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	Rg = 0Ω CTS=20log(V_{OUT}/V_{IN}) BW = IHF-A
	Common Mode Rejection Ratio*	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V_{IN}/V_{OUT}) BW = IHF-A,[*X…D,E]

Electrical Characteristics - continued

BLOCK	Parameter	Symbol	Limit			Unit	Conditions
			Min	Typ	Max		
INPUT GAIN	Minimum Input Gain	G_{IN_MIN}	-2	0	+2	dB	Input gain 0dB V_{IN}=100mVrms G_{IN}=20log(V_{OUT}/V_{IN})
	Maximum Input Gain	G_{IN_MAX}	18	20	22	dB	Input gain 20dB V_{IN}=100mVrms G_{IN}=20log(V_{OUT}/V_{IN})
	Gain Set Error	G_{IN_ERR}	-2	0	+2	dB	GAIN=+20dB to +1dB
MUTE	Mute Attenuation *	G_{MUTE}	-	-105	-85	dB	Mute ON G_{MUTE}=20log(V_{OUT}/V_{IN}) BW = IHF-A
VOLUME	Maximum Gain	G_{V_MAX}	13	15	17	dB	Volume = 15dB V_{IN}=100mVrms G_V=20log(V_{OUT}/V_{IN})
	Maximum Attenuation *	G_{V_MIN}	-	-100	-85	dB	Volume = -∞dB G_V=20log(V V_{OUT}/V_{IN}) BW = IHF-A
	Attenuation Set Error 1	G_{V_ERR1}	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	G_{V_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	G_{V_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
BASS	Maximum Boost Gain	G_{B_BST}	18	20	22	dB	Gain=+20dB f=100Hz V_{IN}=100mVrms G_B=20log (V_{OUT}/V_{IN})
	Maximum Cut Gain	G_{B_CUT}	-22	-20	-18	dB	Gain=-20dB f=100Hz V_{IN}=2Vrms G_B=20log (V_{OUT}/V_{IN})
	Gain Set Error	G_{B_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz
MIDDLE	Maximum Boost Gain	G_{M_BST}	18	20	22	dB	Gain=+20dB f=1kHz V_{IN}=100mVrms G_M=20log (V_{OUT}/V_{IN})
	Maximum Cut Gain	G_{M_CUT}	-22	-20	-18	dB	Gain=-20dB f=1kHz V_{IN}=2Vrms G_M=20log (V_{OUT}/V_{IN})
	Gain Set Error	G_{M_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=1kHz
TREBLE	Maximum Boost Gain	G_{T_BST}	18	20	22	dB	Gain=+20dB f=10kHz V_{IN}=100mVrms G_T=20log (V_{OUT}/V_{IN})
	Maximum Cut Gain	G_{T_CUT}	-22	-20	-18	dB	Gain=-20dB f=10kHz V_{IN}=2Vrms G_T=20log (V_{OUT}/V_{IN})
	Gain Set Error	G_{T_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz
MIXING	Input Impedance	R_{IN_M}	19	27	35	kΩ	
	Maximum Input Voltage	V_{IM_M}	2.0	2.2	-	Vrms	V_{IM} at THD+N(V_{OUT})=1% BW=400Hz-30KHz
	Maximum Attenuation *	G_{MX_MIN}	-	-100	-85	dB	MIX=OFF G_{MX}=20log(V_{OUT}/V_{IN}) BW=INF-A
	Maximum Gain	G_{MX_MAX}	5	7	9	dB	ATT=+7dB G_{MX}=20log(V_{OUT}/V_{IN})

Electrical Characteristics - continued

BLOCK	Parameter	Symbol	Limit			Unit	Conditions
			Min	Typ	Max		
FADER / SUBWOOFER	Maximum Boost Gain	G_{F_BST}	13	15	17	dB	Fader=15dB V_{IN}=100mVrms G_F=20log(V_{OUT}/V_{IN})
	Maximum Attenuation *	G_{F_MIN}	-	-100	-90	dB	Fader = -∞dB G_F=20log(V_{OUT}/V_{IN}) BW = IHF-A
	Gain Set Error	G_{F_ERR}	-2	0	+2	dB	GAIN=+1dB to +15dB
	Attenuation Set Error 1	G_{F_ERR1}	-2	0	+2	dB	ATT=-1dB to -15dB
	Attenuation Set Error 2	G_{F_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	G_{F_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
	Output Impedance	R_{OUT}	-	-	50	Ω	V_{IN} =100mVrms
	Maximum Output Voltage	V_{OM}	2	2.2	-	Vrms	THD+N=1％ BW=400Hz-30KHz

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for * measurement.
Phase between input / output is same.

Typical Performance Curves

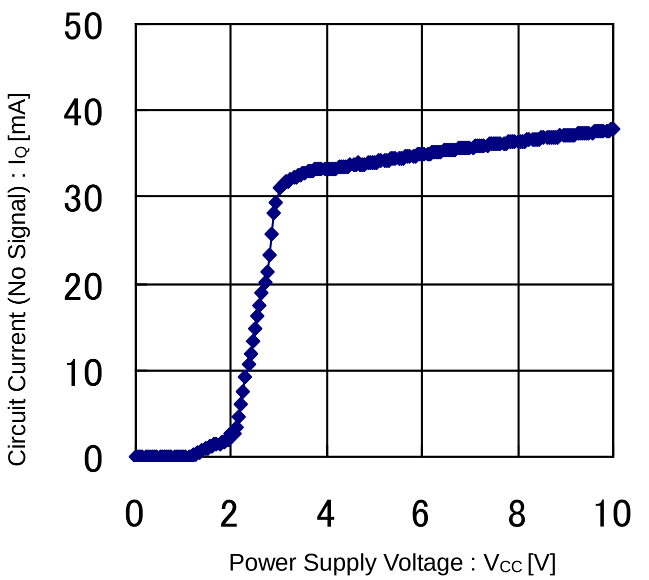


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

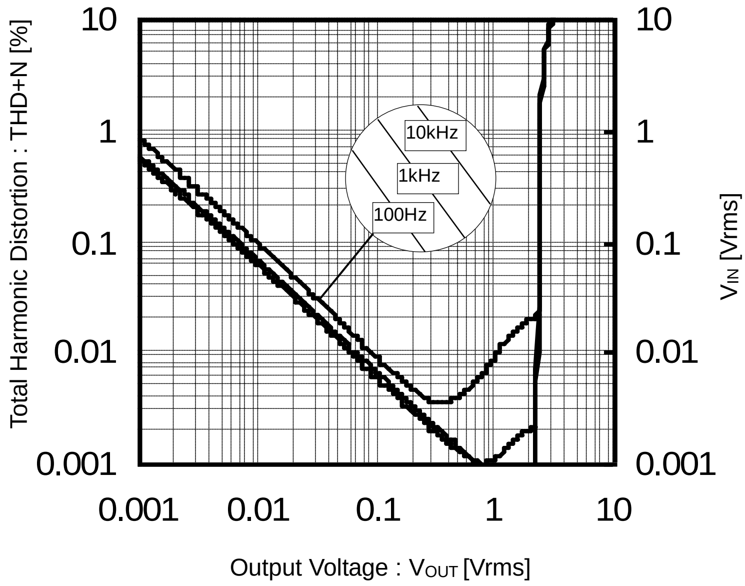


Figure 2. Total Harmonic Distortion vs Output Voltage

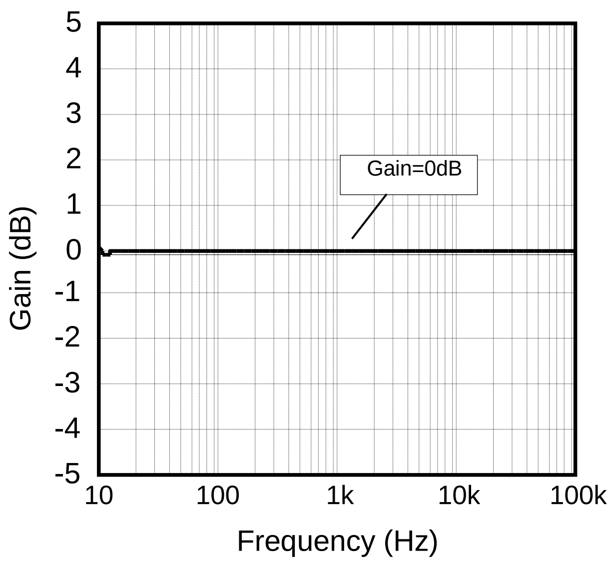


Figure 3. Gain vs Frequency

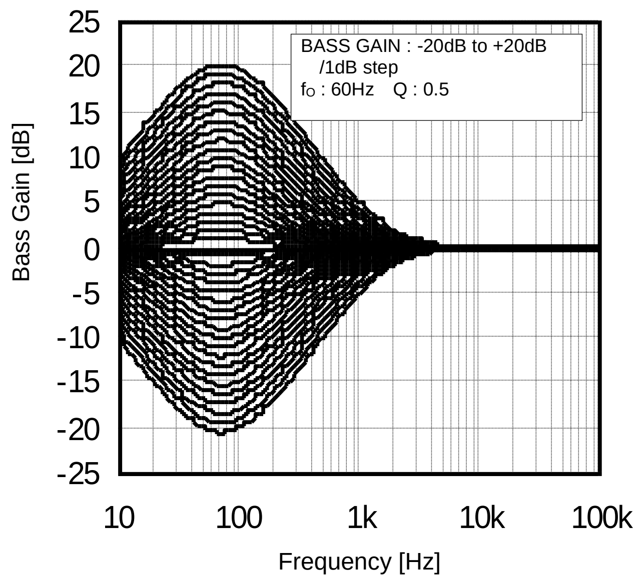


Figure 4. Bass Gain vs Frequency

Typical Performance Curves – continued

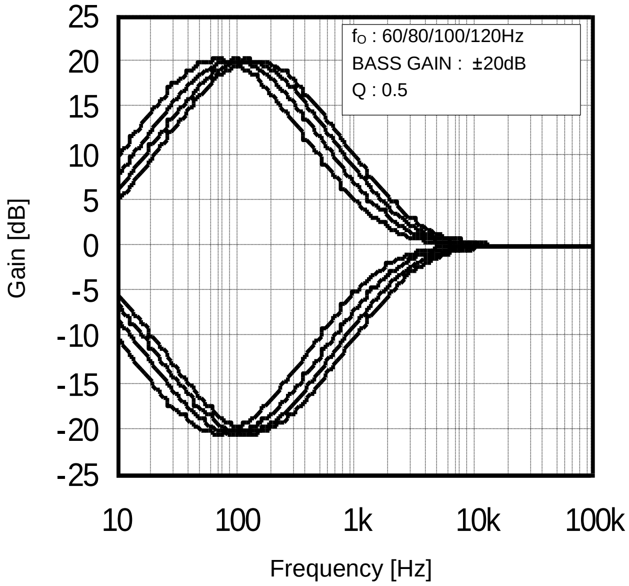


Figure 5. Bass fo vs Frequency

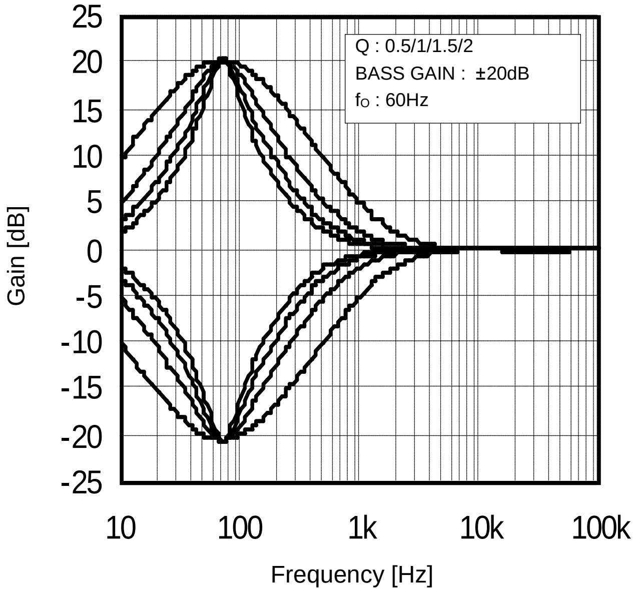


Figure 6. Bass Q vs Frequency

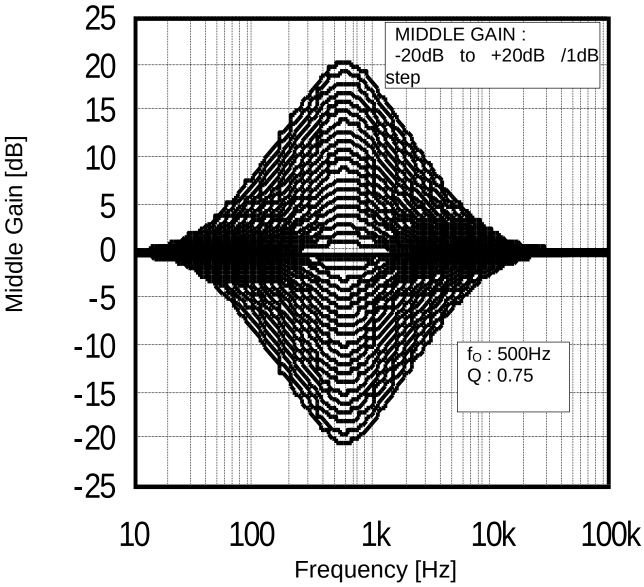


Figure 7. Middle Gain vs Frequency

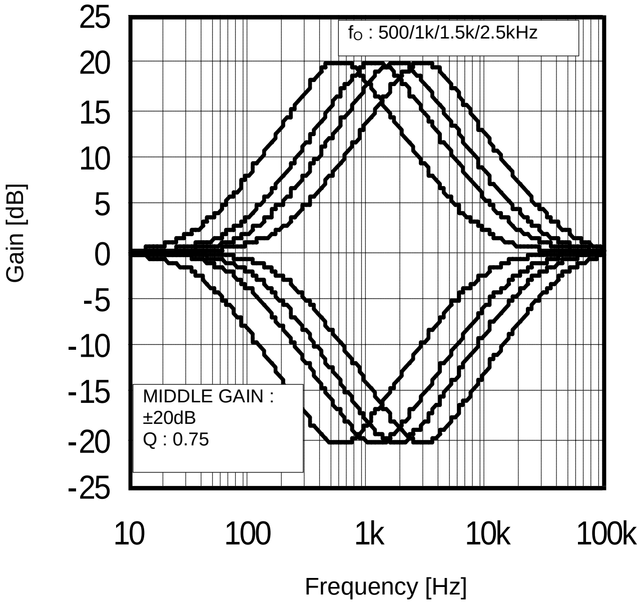


Figure 8. Middle fo vs Frequency

Typical Performance Curves – continued

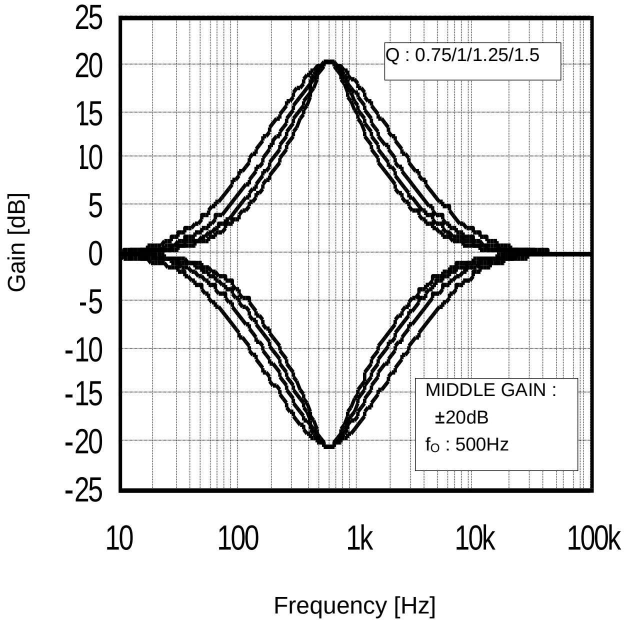


Figure 9. Middle Q vs Frequency

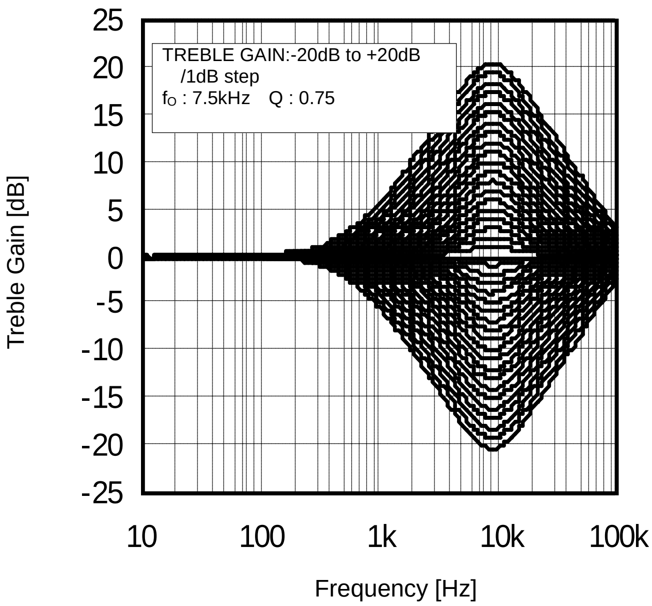


Figure 10. Treble Gain vs Frequency

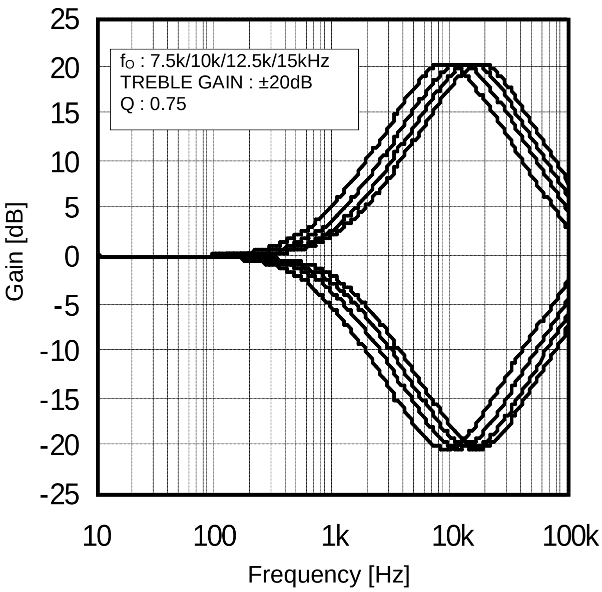


Figure 11. Treble fo vs Frequency

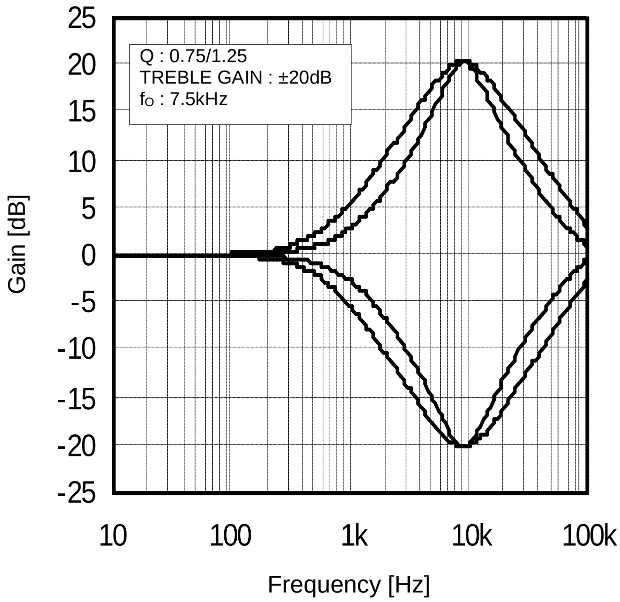


Figure 12. Treble Q vs Frequency

Typical Performance Curves – continued

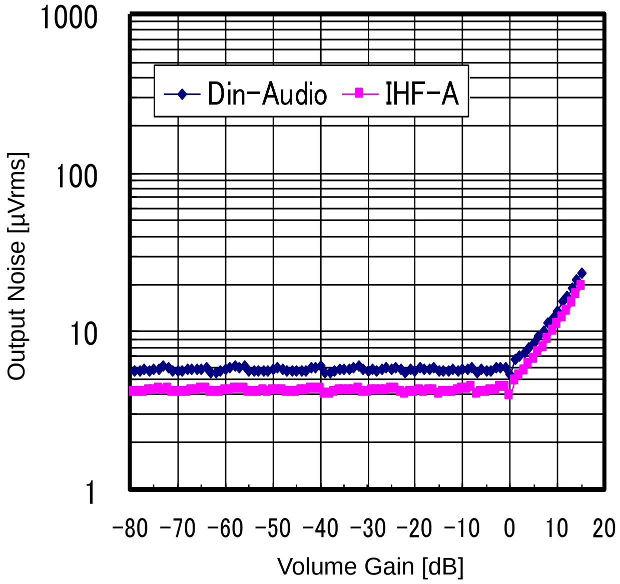


Figure 13. Output Noise vs Volume Gain

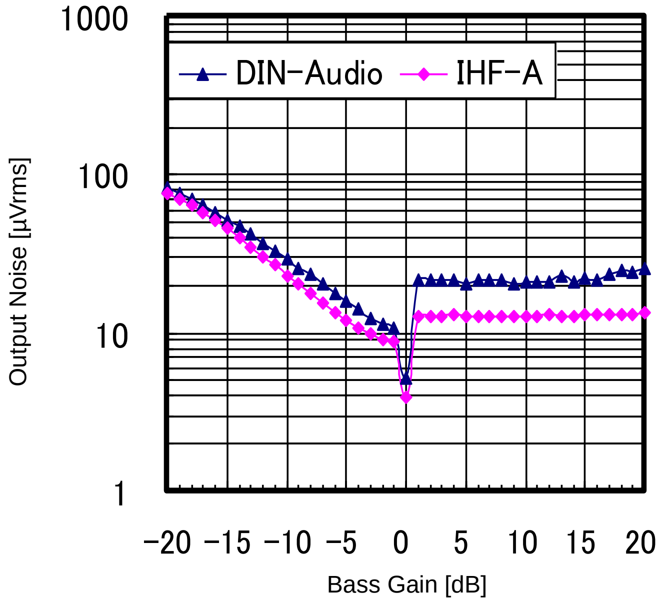


Figure 14. Output Noise vs Bass Gain

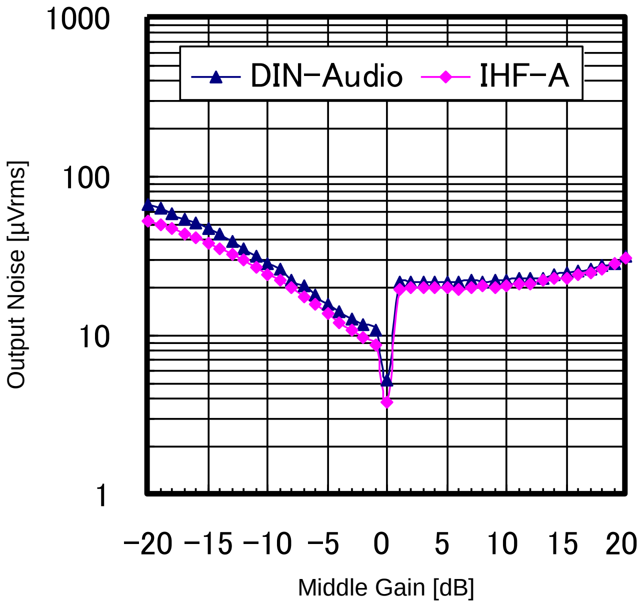


Figure 15. Output Noise vs Middle Gain

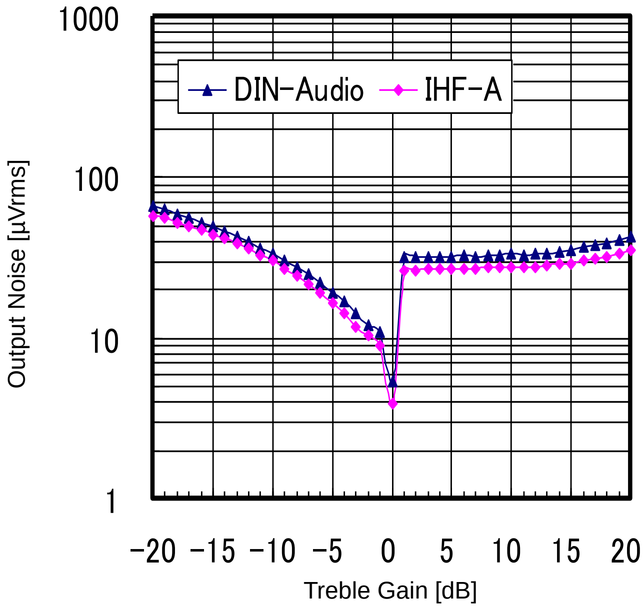


Figure 16. Output Noise vs Treble Gain

Typical Performance Curves – continued

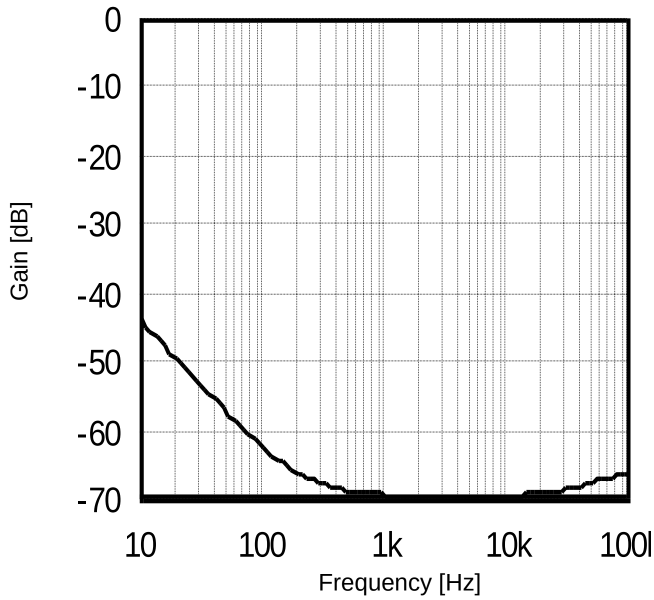


Figure 17. CMRR vs Frequency

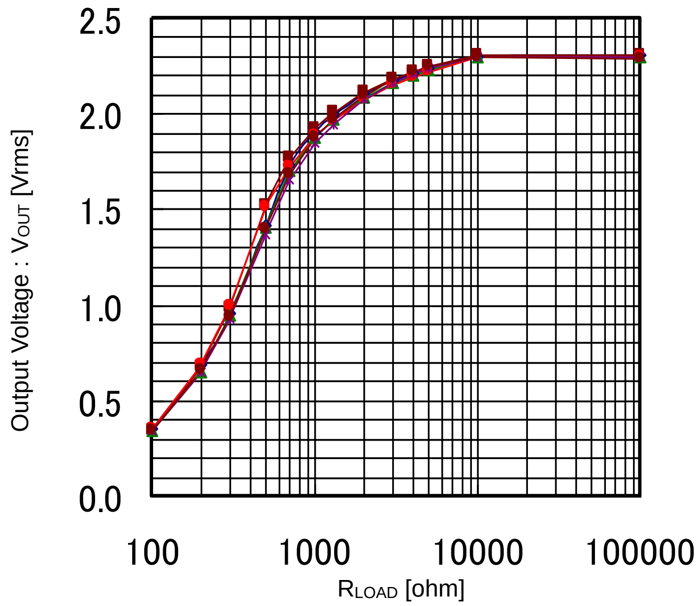


Figure 18. Output Voltage vs R_{LOAD}

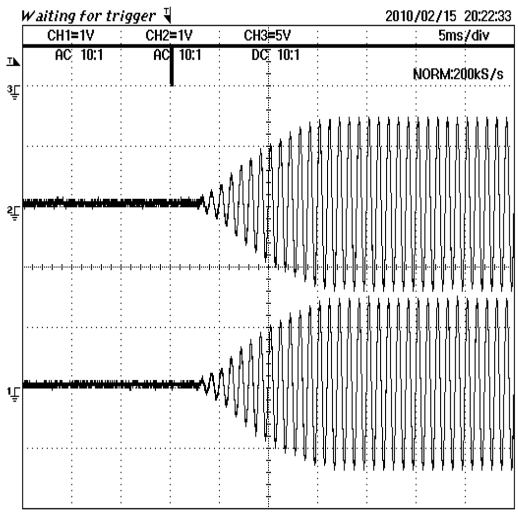


Figure 19. Advanced Switch 1

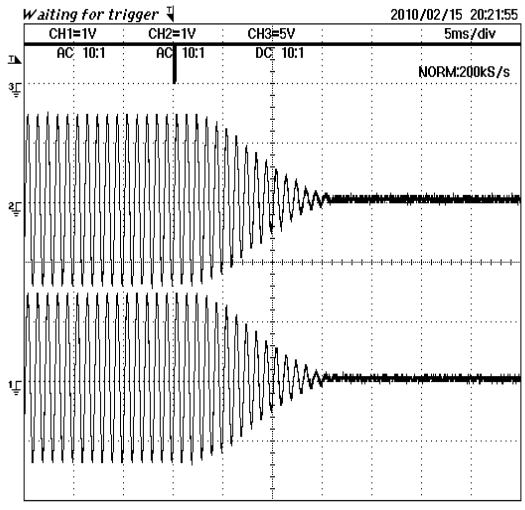


Figure 20. Advanced Switch 2

Timing Chart

CONTROL SIGNAL SPECIFICATION

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

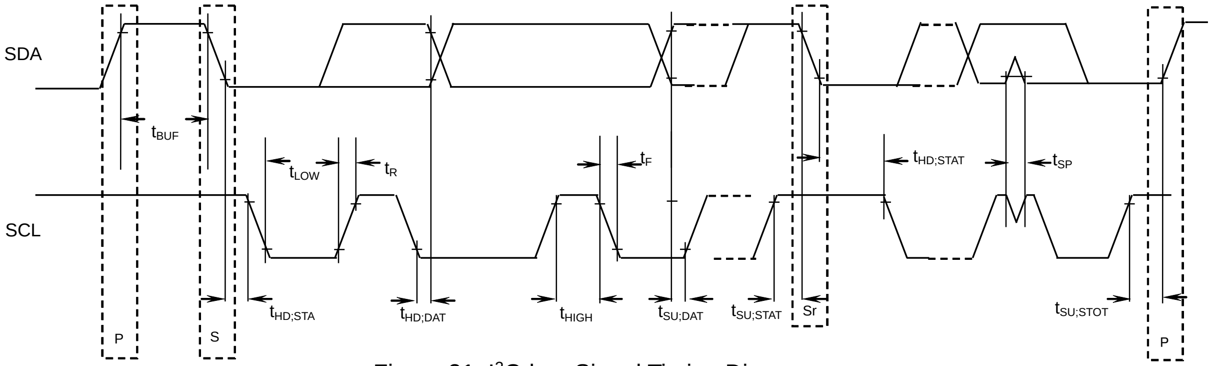


Figure 21. I²C-bus Signal Timing Diagram

Table 1 Characteristics of the SDA and SCL bus lines for I²C-bus devices (Ta=25°C, V_{CC}=8.5V)

Parameter		Symbol	Fast-mode I²C-bus		Unit
			Min	Max	
1	SCL clock frequency	f_{SCL}	0	400	kHz
2	Bus free time between a STOP and START condition	t_{BUF}	1.3	-	μS
3	Hold time (repeated) START condition. After this period, the first clock pulse is generated	$t_{HD;STA}$	0.6	-	μS
4	LOW period of the SCL clock	t_{LOW}	1.3	-	μS
5	HIGH period of the SCL clock	t_{HIGH}	0.6	-	μS
6	Set-up time for a repeated START condition	$t_{SU;STA}$	0.6	-	μS
7	Data hold time:	$t_{HD;DAT}$	0.06 (Note)	-	μS
8	Data set-up time	$t_{SU;DAT}$	120	-	ns
9	Set-up time for STOP condition	$t_{SU;STO}$	0.6	-	μS

All values refer to VIH Min and VIL Max Levels (see Table 2).

(Note) A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.
For 7($t_{HD;DAT}$), 8($t_{SU;DAT}$), make the setup in which the margin is full.

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

Parameter		Symbol	Fast-mode devices		Unit
			Min	Max	
10	LOW level input voltage:	V_{IL}	-0.3	+1	V
11	HIGH level input voltage:	V_{IH}	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	t_{SP}	0	50	ns
13	LOW level output voltage: at 3mA sink current	V_{OL1}	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	I_I	-10	+10	μA

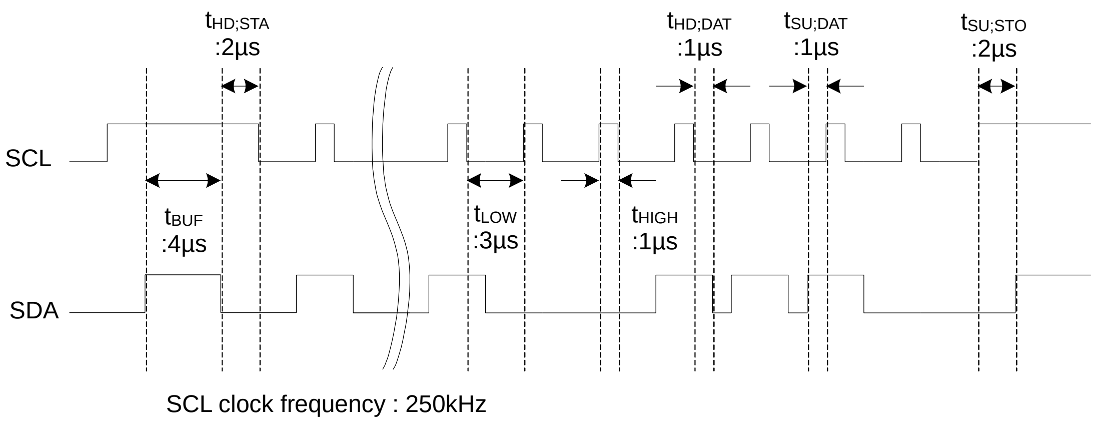


Figure 22. A Command Timing Example in the I²C Data Transmission

(2) I^2C BUS FORMAT

S	Slave Address	A	Select Address	A	Data	A	P
	MSB LSB		MSB LSB		MSB LSB		
1bit	8bit	1bit	8bit	1bit	8bit	1bit	1bit

S = Start condition (Recognition of start bit)
Slave Address = Recognition of slave address. The first 7 bits correspond to the slave address. The least significant bit is "L" which corresponds to write mode.
A = ACKNOWLEDGE bit (Recognition of acknowledgement)
Select Address = Select address corresponding to volume, bass or treble.
Data = Data on every volume and tone.
P = Stop condition (Recognition of stop bit)

(3) I^2C BUS Interface Protocol

(a) Basic Format

S	Slave Address	A	Select Address	A	Data	A	P
	MSB LSB		MSB LSB		MSB LSB		

(b) Automatic Increment (Select Address increases (+1) according to the number of data.)

S	Slave Address	A	Select Address	A	Data1	A	Data2	A	····	DataN	A	P
	MSB LSB		MSB LSB		MSB LSB		MSB LSB			MSB LSB		

(Example)

① Data1 shall be set as data of address specified by Select Address.
② Data2 shall be set as data of address specified by Select Address +1.
③ DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration Unavailable for Transmission (In this case, only Select Address1 is set.)

S	Slave Address	A	Select Address1	A	Data	A	Select Address 2	A	Data	A	P
	MSB LSB		MSB LSB		MSB LSB		MSB LSB		MSB LSB		

(Note) If any data is transmitted as Select Address 2 next to data, it is recognized as data, not as Select Address 2.

(4) Slave Address

MSB LSB

A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

(5) Select Address & Data

Items	Select Address (hex)	MSB			Data				LSB
		D7	D6	D5	D4	D3	D2	D1	D0
Initial setup 1	01	Advanced switch ON/OFF	0	Advanced switch time of Input Gain/Volume Tone/Fader/Super Bass Mixing		0	1	Advanced switch time of Mute	
Initial setup 2	02	LPF Phase	0	Subwoofer Output Select		0	Subwoofer LPF fC		
Initial setup 3	03	Front HPF Pass	Rear HPF Pass	Front / Rear HPF fC			0	1	0
Input Selector	05	Full-diff Type	0	0	Input selector				
Input gain	06	Mute ON/OFF	0	0	Input Gain				
Volume gain	20	Volume Gain / Attenuation							
Fader 1ch Front	28	Fader Gain / Attenuation							
Fader 2ch Front	29	Fader Gain / Attenuation							
Fader 1ch Rear	2A	Fader Gain / Attenuation							
Fader 2ch Rear	2B	Fader Gain / Attenuation							
Fader Subwoofer	2C	Fader Gain / Attenuation							
Mixing	30	Mixing Gain / Attenuation							
Bass setup	41	0	0	Bass fO		0	0	Bass Q	
Middle setup	44	0	0	Middle fO		0	0	Middle Q	
Treble setup	47	0	0	Treble fO		0	0	0	Treble Q
Bass gain	51	Bass Boost/ Cut	0	0	Bass Gain				
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain				
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain				
Super Bass Gain	75	0	0	0	Super Bass Gain				
System Reset	FE	1	0	0	0	0	0	0	1

Advanced switch

Note

1. The Advanced Switch works in the latch part while changing from one function to another.
2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

→01→02→03→05→06→20→28→29→2A→2B→2C

→30→41→44→47→51→54→57→75

.

3. Advanced switch is not used for the function of input selector and subwoofer output select, etc. Therefore, please apply mute on the side when changing these settings.
4. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF for waiting advanced-mute time.

Select address 01 (hex)

Time	MSB Advanced switch time of Mute							LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	Advanced Switch ON/OFF	0	Advanced switch time of Input gain/Volume Tone/Fader/Super Bass/Mixing		0	1	0	0
1.0msec							0	1
1.4msec							1	0
3.2msec							1	1

Time	MSB Advanced switch time of Input gain/Volume/Tone/Fader/ Super Bass/Mixing							LSB
	D7	D6	D5	D4	D3	D2	D1	D0
4.7 msec	Advanced Switch ON/OFF	0	0	0	0	1	Advanced switch Time of Mute	
7.1 msec			0	1				
11.2 msec			1	0				
14.4 msec			1	1				

Mode	MSB Advanced switch ON/OFF							LSB
	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	Advanced switch time of Input gain/Volume Tone/Fader/Super Bass/Mixing		0	1	Advanced switch Time of Mute	
ON	1							

Select address 02(hex)

f_C	MSB Subwoofer LPF f_C							LSB
	D7	D6	D5	D4	D3	D2	D1	D0
OFF	LPF Phase	0	Subwoofer Output Select		0	0	0	0
55Hz						0	0	1
85Hz						0	1	0
120Hz						0	1	1
160Hz						1	0	0
Prohibition						Other setting		

Mode	MSB Subwoofer Output Select							LSB
	D7	D6	D5	D4	D3	D2	D1	D0
LPF	LPF Phase	0	0	0	0	Subwoofer LPF f_C		
Front			0	1				
Rear			1	0				
Prohibition			1	1				

Phase	MSB LPF Phase							LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0°	0	0	Subwoofer output select		0	Subwoofer LPF f_C		
180°	1							

: Initial condition

Select address 03(hex)

Mode	MSB D7	D6	Front/Rear HPF fc D5	D4	D3	D2	D1	LSB D0
55Hz	Front HPF Pass	Rear HPF Pass	0	0	0	0	1	0
85Hz			0	0	1			
120Hz			1	1	0			
160Hz			0	1	0			
Prohibition			Other setting					

Mode	MSB D7	Rear HPF D6	D5	D4	D3	D2	D1	LSB D0
pass	Front HPF Pass	0	Front/Rear HPF fc			0	1	0
NOT pass		1						

Mode	MSB Front HPF D7	D6	D5	D4	D3	D2	D1	LSB D0
pass	0	Rear HPF Pass	Front/Rear HPF fc			0	1	0
NOT pass	1							

Select address 05(hex)

Mode	OUTF1	OUTF2	MSB D7	D6	D5	Input Selector D4	D3	D2	D1	LSB D0
A	A1	A2	Full-diff bias type select	0	0	0	0	0	0	0
B	B1	B2				0	0	0	0	1
C	C1	C2				0	0	0	1	0
D single	DP1	DP2				0	0	0	1	1
E single	EP1	EP2				0	0	1	0	0
A diff	A1	B1				0	1	1	1	1
C diff	B2	C2				1	0	0	0	0
D diff	DP1	DP2				0	0	1	1	0
E diff	EP1	EP2				0	0	1	1	1
Input SHORT						0	1	0	0	1
Prohibition						Other setting				

Input SHORT : The input impedance of each input terminal is lowered from 100kΩ(Typ) to 6 kΩ(Typ).
(For quick charge of coupling capacitor)

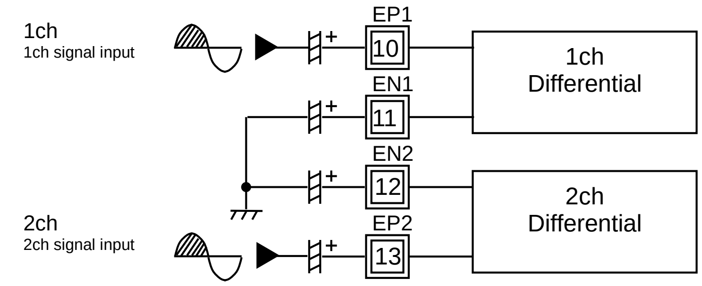
: Initial condition

Select address 05(hex)

Mode	MSB			Full-diff Bias Type Select				LSB
	D7	D6	D5	D4	D3	D2	D1	D0
Negative Input	0	0	0	Input Selector				
Bias	1							

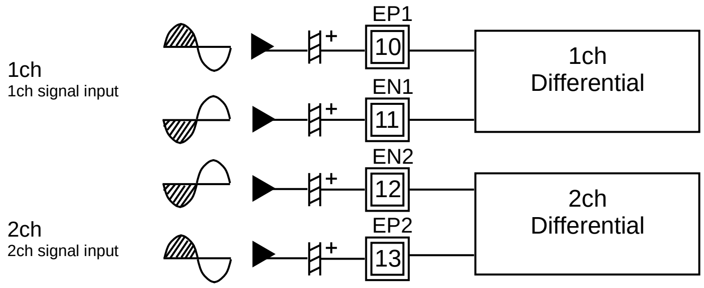
Negative input type

For Ground –isolation type.



Bias type

For differential amplifier type



Select address 06 (hex)

Gain	MSB			Input Gain				LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0dB	Mute ON/OFF	0	0	0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB				0	1	0	1	1
12dB				0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
Prohibition				1	1	0	1	1
				:	:	:	:	:
				1	1	1	1	1

: Initial condition

Select address 06 (hex)

Mode	MSB D7	D6	D5	Mute ON/OFF D4	D3	D2	D1	LSB D0
OFF	0	0	0	Input Gain				
ON	1							

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB D7	D6	D5	Vol, Fader Gain / Attenuation D4	D3	D2	D1	LSB D0
Prohibition	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
Prohibition	1	1	0	1	0	0	0	0
	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 30(hex)

Gain & ATT	MSB D7	D6	D5	Mixing Gain / Attenuation D4	D3	D2	D1	LSB D0
Prohibition	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
	:	:	:	:	:	:	:	:
	0	1	1	1	1	0	0	0
7dB	0	1	1	1	1	0	0	1
6dB	0	1	1	1	1	0	1	0
5dB	0	1	1	1	1	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
Prohibition	1	1	0	1	0	0	0	0
	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
MIX OFF	1	1	1	1	1	1	1	1

(Note) See the precaution on P30 together, too.

: Initial condition

Select address 41(hex)

Q factor	MSB		Bass Q factor					LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0.5	0	0	Bass fO		0	0	0	0
1.0							0	1
1.5							1	0
2.0							1	1

fO	MSB		Bass fO					LSB
	D7	D6	D5	D4	D3	D2	D1	D0
60Hz	0	0	0	0	0	0	Bass Q factor	
80Hz			0	1				
100Hz			1	0				
120Hz			1	1				

Select address 44(hex)

Q factor	MSB		Middle Q factor					LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Middle fO		0	0	0	0
1.0							0	1
1.25							1	0
1.5							1	1

fO	MSB		Middle fO					LSB
	D7	D6	D5	D4	D3	D2	D1	D0
500Hz	0	0	0	0	0	0	Middle Q factor	
1kHz			0	1				
1.5kHz			1	0				
2.5kHz			1	1				

Select address 47 (hex)

Q factor	MSB		Treble Q factor					LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Treble fO		0	0	0	0
1.25								1

fO	MSB		Treble fO					LSB
	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz	0	0	0	0	0	0	0	Treble Q factor
10kHz			0	1				
12.5kHz			1	0				
15kHz			1	1				

: Initial condition

Select address 51, 54, 57 (hex)

Gain	MSB D7	D6	D5	D4	D3	D2	D1	LSB D0
0dB	Bass/Middle/Treble Boost/cut	0	0	0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB				0	1	0	1	1
12dB				0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
Prohibition				1	0	1	0	1
				:	:	:	:	:
				1	1	1	1	0
				1	1	1	1	1

Mode	MSB D7	D6	D5	D4	D3	D2	D1	LSB D0
Boost	0	0	0	Bass/Middle/Treble Gain				
Cut	1							

: Initial condition

Select address 75 (hex)

Gain	D7 (MSB)	D6	D5	D4	D3	D2	D1	D0 (LSB)
	Super Bass Gain							
0dB	0	0	0	0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB				0	1	0	1	1
12dB				0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
Prohibition				1	0	1	0	1
				:	:	:	:	:
				1	1	1	1	1

(Note) About Super Bass, the above Gain is for in indication purposes. Actual Gain (=20log (V_{OUT}/V_{IN})) is different. Refer to P31 to P34 for the details.

: Initial condition

(6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn ON mute until this initial data is sent.

Parameter	Symbol	Limit Min	Limit Typ	Limit Max	Unit	Conditions
Rise Time of VCC	t_{RISE}	33	-	-	µsec	V_{CC} rise time from 0V to 5V
VCC Voltage of Release Power ON Reset	V_{POR}	-	4.1	-	V	

Application Information

1. Function and Specifications

Function	Specifications
Input selector	・ Stereo input ・ Single-End/Differential (Possible to set the number of single-end/ differential as follows) <table><tr><th></th><th>Single-End</th><th>Differential</th></tr><tr><td>Mode 1</td><td>0</td><td>4</td></tr><tr><td>Mode 2</td><td>1</td><td>3</td></tr><tr><td>Mode 3</td><td>3</td><td>2</td></tr><tr><td>Mode 4</td><td>4</td><td>1</td></tr><tr><td>Mode 5</td><td>5</td><td>0</td></tr></table>Table.1 Combination of input selector
Input gain	・ +20dB to 0dB (1dB step) ・ Possible to use “Advanced switch” for prevention of switching noise.
Mute	・ Possible to use “Advanced switch” for prevention of switching noise.
Volume	・ +15dB to -79dB (1dB step), -∞dB ・ Possible to use “Advanced switch” for prevention of switching noise.
Bass	・ +20dB to -20dB (1dB step) ・ Q=0.5, 1, 1.5, 2 ・ f_O=60, 80, 100, 120Hz ・ Possible to use “Advanced switch” for prevention of switching noise.
Middle	・ +20dB to -20dB (1dB step) ・ Q=0.75, 1, 1.25, 1.5 ・ f_O=500, 1k, 1.5k 2.5kHz ・ Possible to use “Advanced switch” for prevention of switching noise.
Treble	・ +20dB to -20dB (1dB step) ・ Q=0.75, 1.25 ・ f_O=7.5k, 10k, 12.5k, 15kHz ・ Possible to use “Advanced switch” for prevention of switching noise.
Fader	・ +15dB to -79dB(1dB step), -∞dB ・ Possible to use “Advanced switch” for prevention of switching noise.
LPF	・ f_C=55/85/120/160Hz, pass ・ Phase shift (0°/180°)
HPF	・ f_C=55/85/120/160Hz, pass
Mixing	・ Monaural input ・ +7dBdB to -79dB (1dB step), -∞dB ・ Possible to use “Advanced switch” for prevention of switching noise.
Super Bass	・ +20dB to 0dB (1dB step) ・ Possible to use “Advanced switch” for prevention of switching noise.

2. **Volume / Fader Volume / Mixing ATT Attenuation Data**

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6	1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9	1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10	1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11	1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-∞	1	1	1	1	1	1	1	1

Adjustable range of mixing ATT is +7dB to -∞dB.

: Initial condition

3. Application Circuit

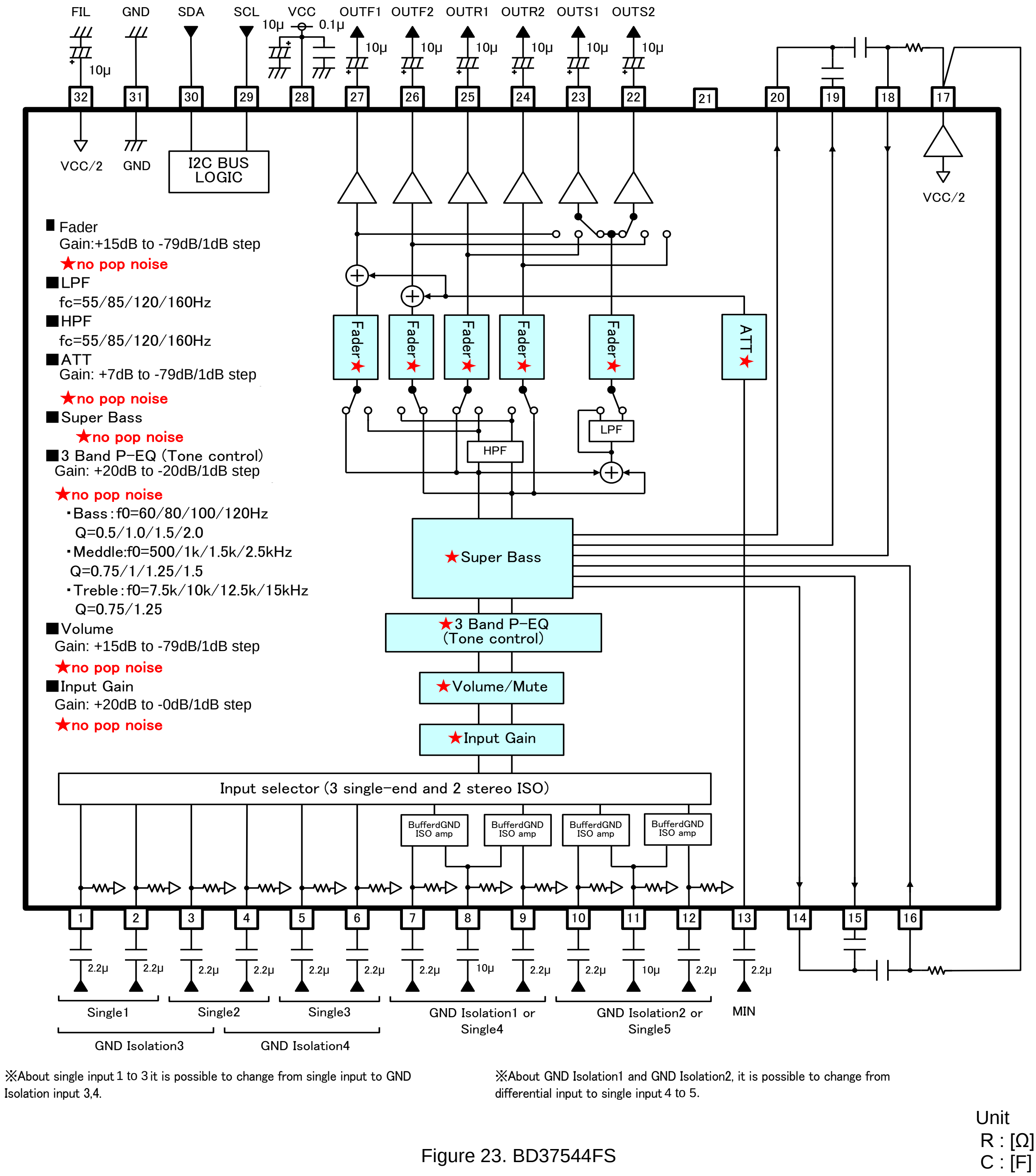


Figure 23. BD37544FS

Notes on wiring

①Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
②GND lines should be one-point connected.
③Wiring pattern of Digital should be away from that of Analog unit and cross-talk should not be acceptable.
④SCL and SDA lines of I²C BUS should not be parallel if possible.
The lines should be shielded, if they are adjacent to each other.
⑤Analog input lines should not be parallel if possible. The lines should be shielded, if they are adjacent.
⑥Please short Pins 15-16, and Pins 18-19 if the Super Bass is not used.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy elements. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

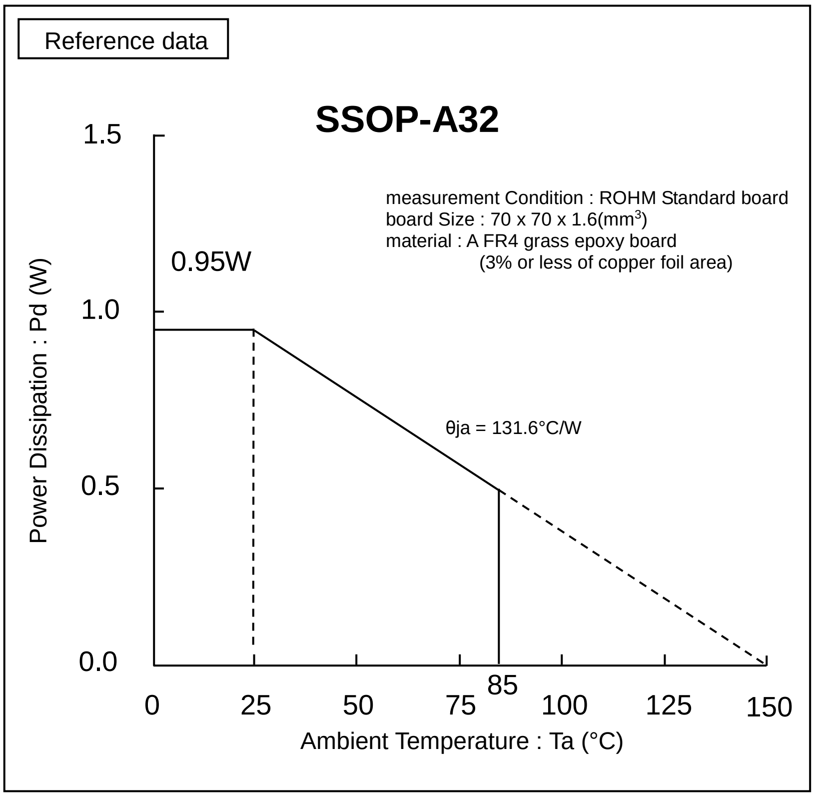
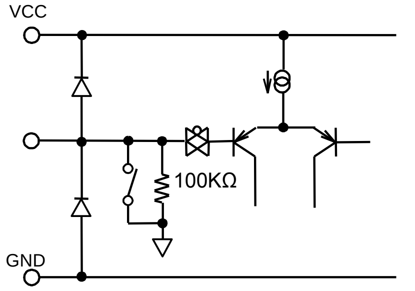
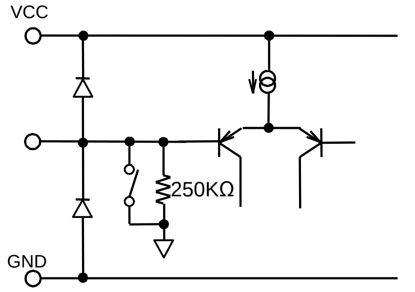
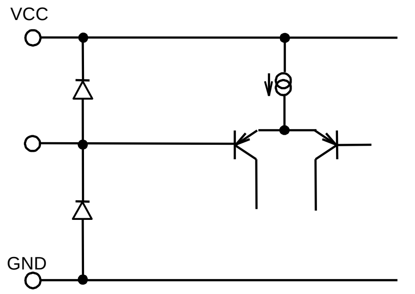
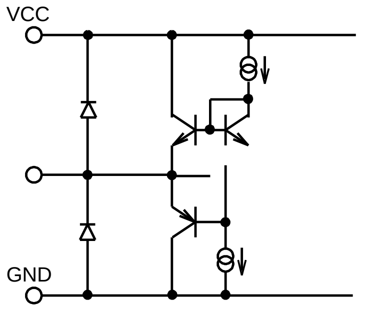
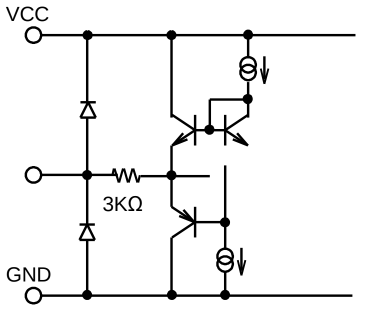


Figure 24. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

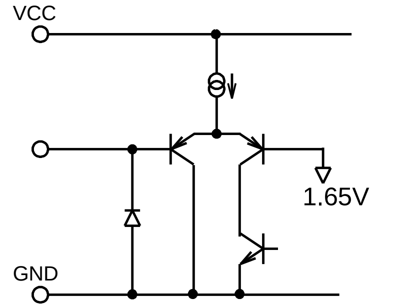
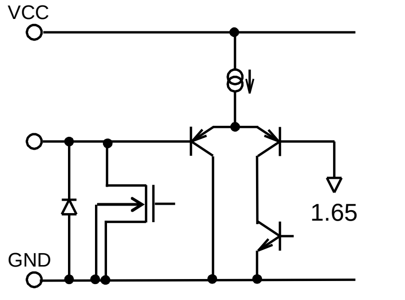
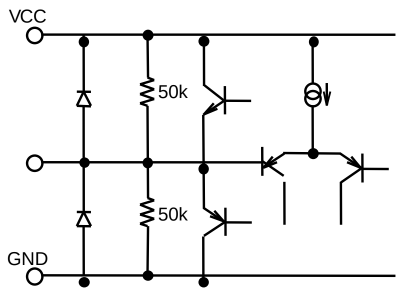
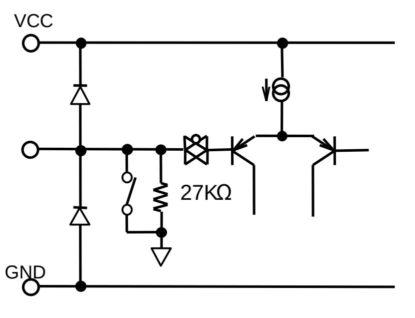
Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25		A terminal for signal input. The input impedance is 100kΩ(Typ).
7 8 9 10 11 12	DP1 DN DP2 EP1 EN EP2	4.25		Input terminal available to ingle/Differential mode. The input impedance is 250kΩ(Typ).
16 18	SBB1 SBB2	-		An input terminal for Super Bass
15 17 19 22 23 24 25 26 27	SBA1 SBBIAS SBA2 OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25		A terminal for Super Bass and fader, Subwoofer output.
14 20	SBC1 SBC2	4.25		An output terminal for Super Bass.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

I/O Equivalent Circuits – continued

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
28	VCC	8.5		Power supply terminal.
29	SCL	-		A terminal for clock input of I^{2}C BUS communication.
30	SDA	-		A terminal for data input of I^{2}C BUS communication.
31	GND	0		Ground terminal.
32	FIL	4.25		1/2 VCC terminal. Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.
13	MIN	4.25		A terminal for signal input. The input impedance is 27kΩ(typ).

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

Operational Notes

1. **Reverse Connection of Power Supply**
   Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. **Power Supply Lines**
   Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. **Ground Voltage**
   Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. **Ground Wiring Pattern**
   When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. **Thermal Consideration**
   Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. **Recommended Operating Conditions**
   These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. **Inrush Current**
   When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. **Operation Under Strong Electromagnetic Field**
   Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. **Testing on Application Boards**
   When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. **Inter-pin Short and Mounting Errors**
    Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. **Unused Input Pins**
    Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

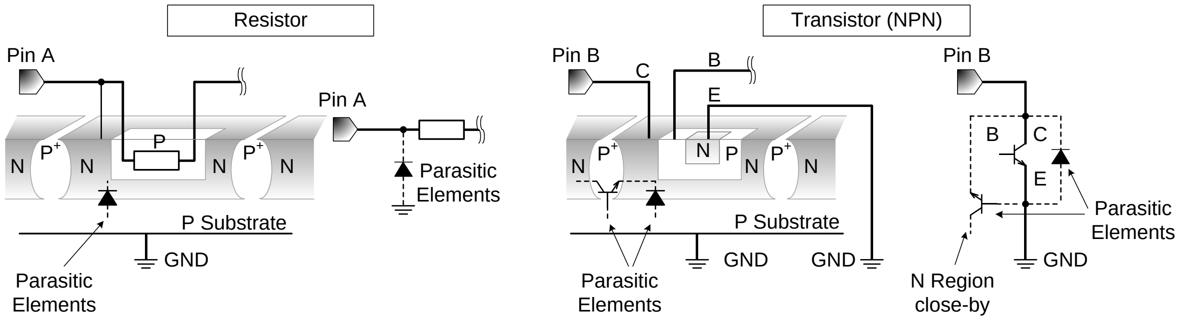
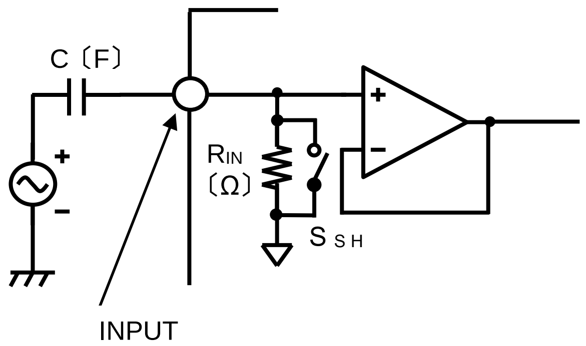


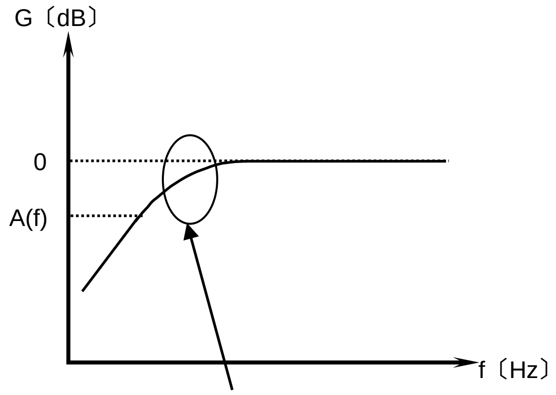
Figure 25. Example of monolithic IC structure

13. About Signal Input

(a) About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance R_{IN}(Ω) at the input signal terminal of the IC. The first HPF characteristic of RC is composed.





$$A(f) = \sqrt{\frac{(2\pi fCR_{IN})^2}{1+(2\pi fCR_{IN})^2}}$$

(b) About the Input Selector SHORT

SHORT mode is the command which makes switch S_{SH} =ON of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected.
The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

Operational Notes – continued

14. About MIX

(1) <u>About Specification of Fader -∞ at MIX ON.</u>
Mix_signal is added to Main_signal after Fader_Gain(+15dB to -79dB) like the figure. When Fader is set at -∞, the signal after a MIX signal is added is done with MUTE because the -∞ circuit of Fader is in the step after the addition circuit

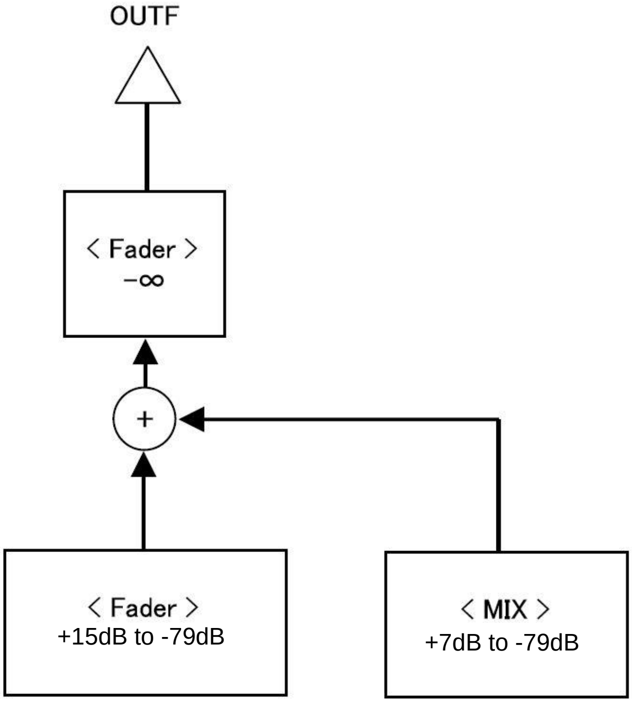
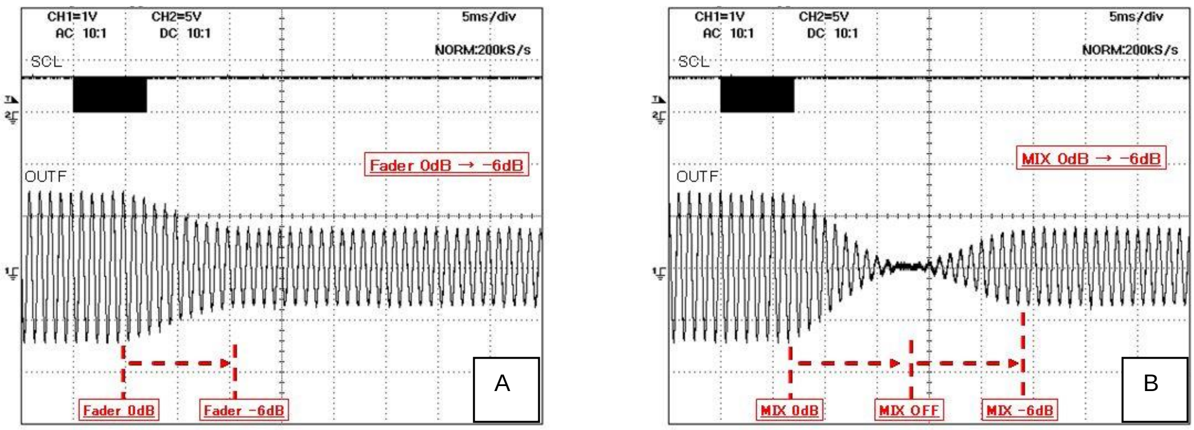


Figure 26. About Front Fader and MIX

(2) <u>About Advanced Switching of MIX_Gain/ATT</u>
When advanced switching of MIX_Gain/ATT works, MIX goes a switching movement that it passes through the state of MIX_OFF like in B figure below (from current settingof MIX_Gain/ATT to MIX_OFF to a target setting of MIX_Gain/ATT).



Fader_Gain/ATT 0dB to -6dB advanced switching

MIX_Gain/ATT 0dB to -6dB advanced switching

Figure 27. Advanced Switching Movement when MIX_Gain/ATT is Changed

Operational Notes – continued

15. About Super Bass Circuit

The (the following Super Bass) which strengthens a low band like the graph below a can be realized by composing an external circuit with the pin 14 to 20 as shown in Figure 28.

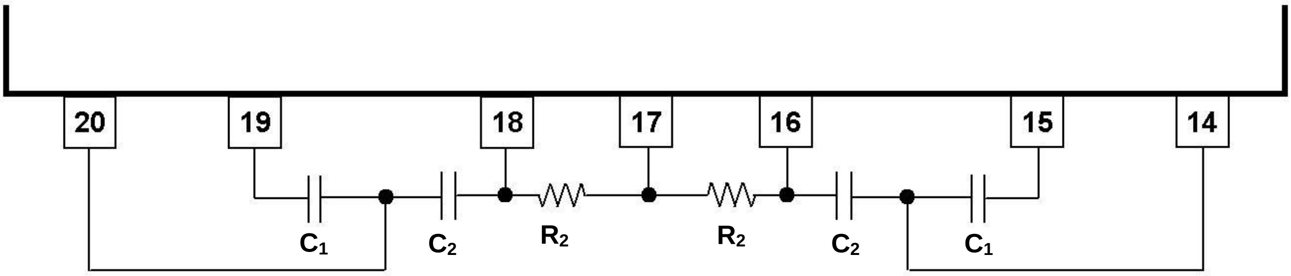


Figure 28. Super Bass circuit

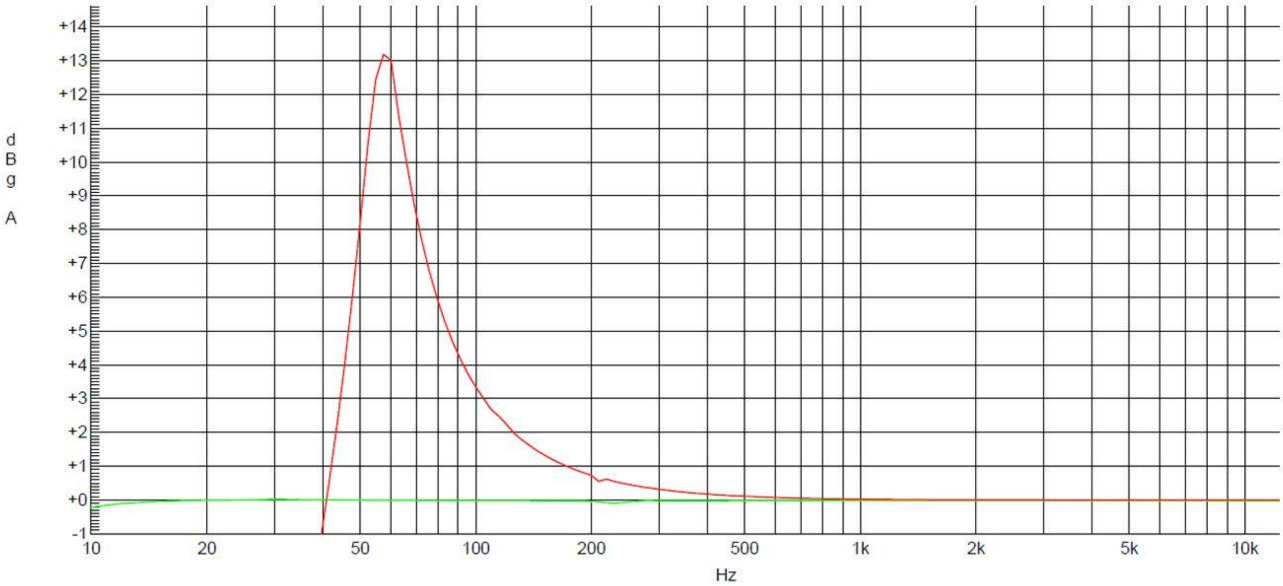


Figure 29. Super Bass Gain vs Frequency

(a) Gain Step Width becomes a Logarithm

When a setup of Gain is made 0,1,2,3,5,7,11,20dB, it becomes the following (bottom right) character.
(C_1=0.047µF, C_2=0.1µF, R_1=3kΩ, R_2=560kΩ)

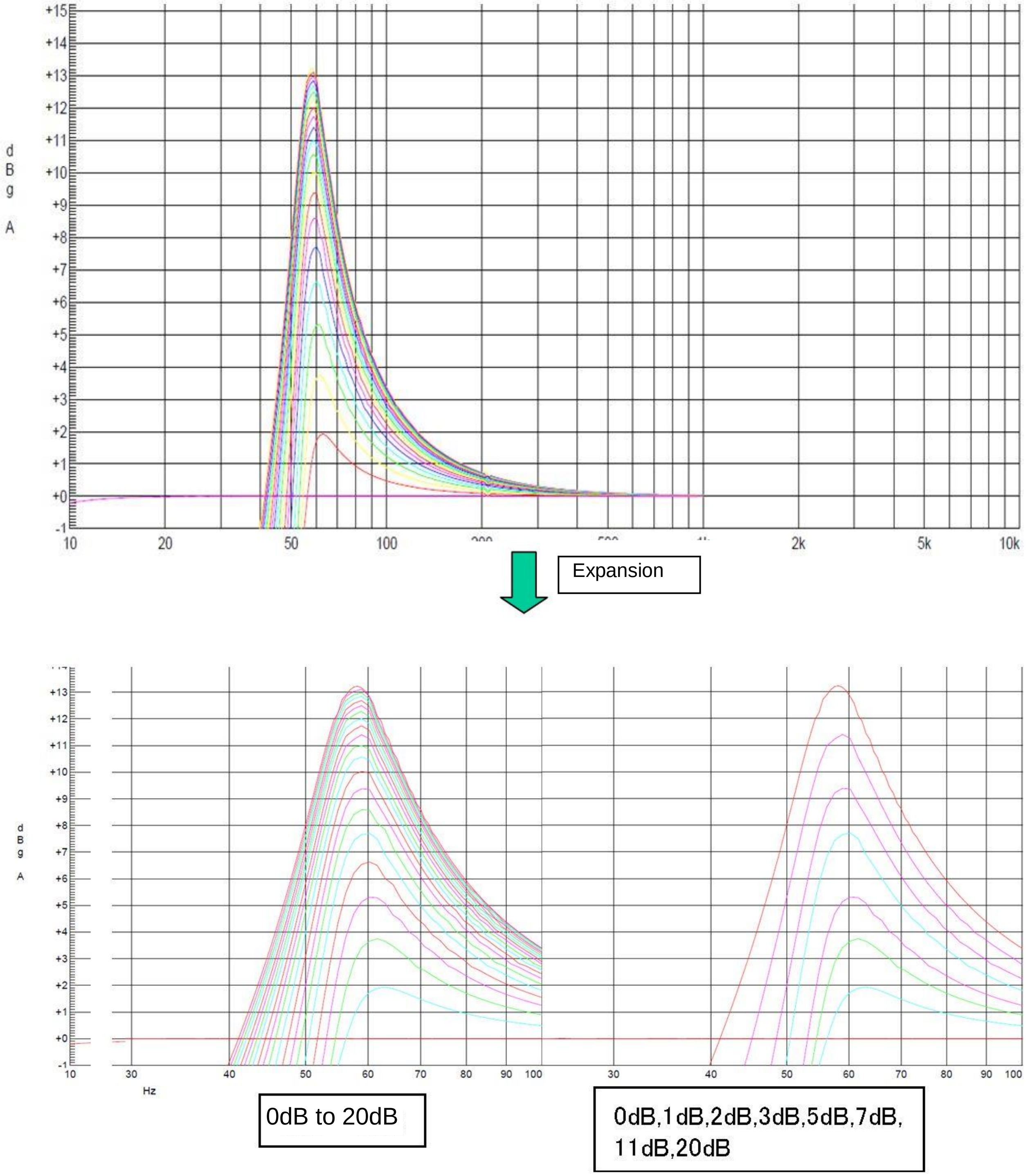
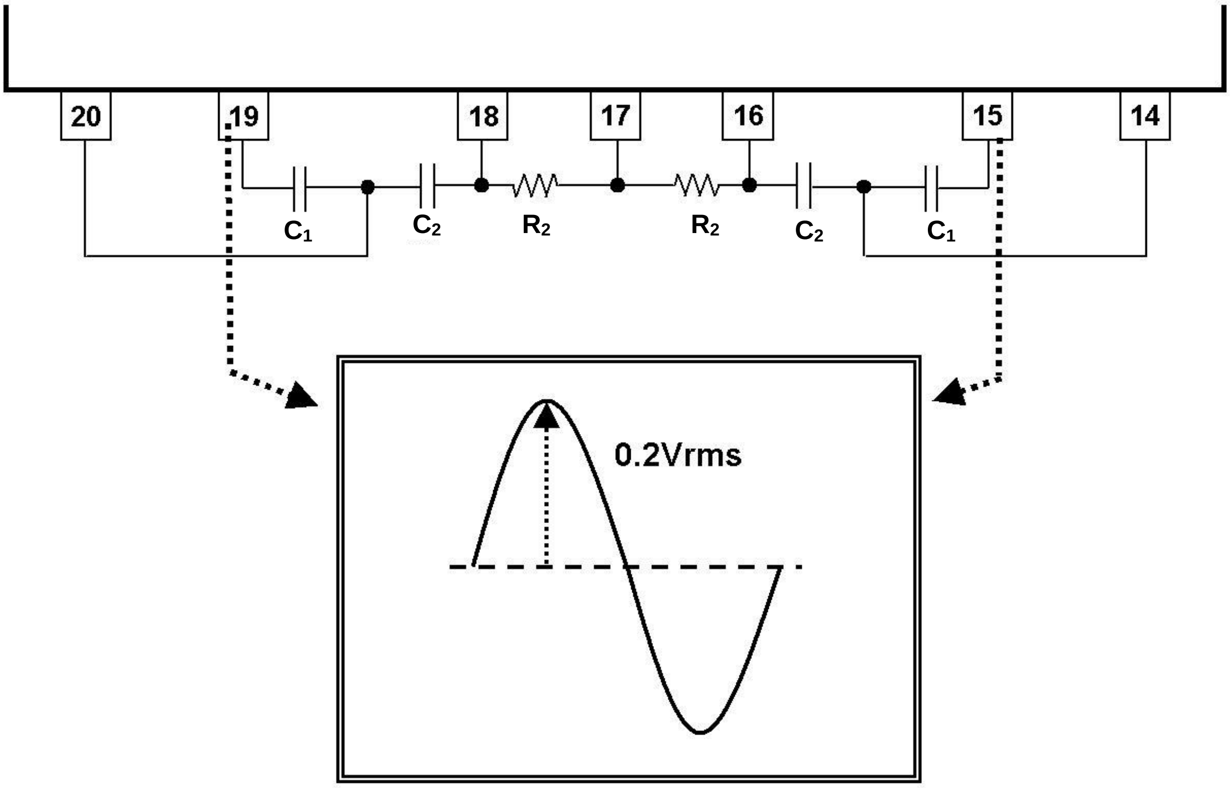


Figure 30. About Gain step of Super Bass

(b) You must take level diagram into consideration so that output may not do a clip

Example (C_1=0.047µF, C_2=0.1µF, R_2=560kohm, V_{CC}=8.5V)
To prevent output clipping due to amplification when Super Bass is used, adjust the level diagram with volume until the Tone output level becomes less than 0.2Vrms.



Please adjust so that the maximum level of the Tone output becomes less than 0.2Vrms. (at V_{CC}=8.5V)

Figure 31. Super Bass Level Diagram

(c) About f_O and Gain of Super Bass

f_O and Gain of Super Bass deviates due to the deviation of the value of C_1, C_2, R_2 (Components with the outside),
R_1 (the resistance built in IC).

Example：Super Bass Gain – frequency characteristic at Dispersion condition of C_1,C_2,R_2±5%, R_1±30%
(C_1=0.047μF, C_2=0.1μF, R_1=3kohm, R_2=560kohm, Super Bass Gain=20dB)

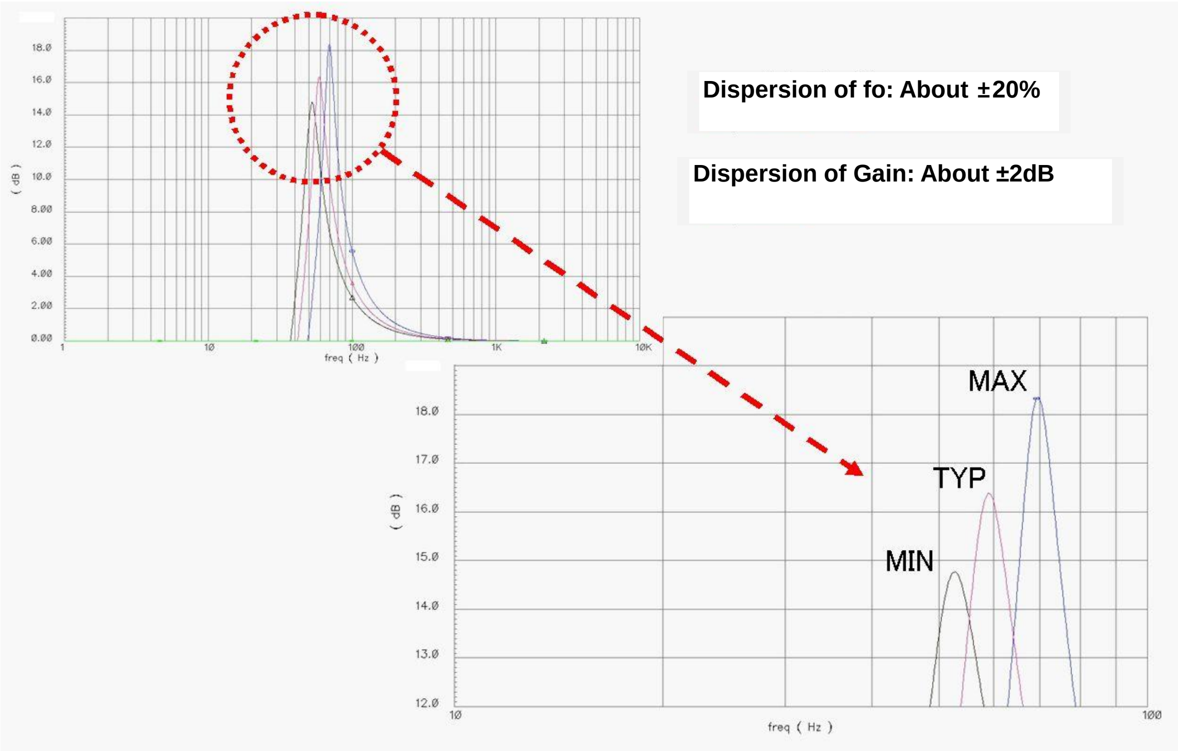
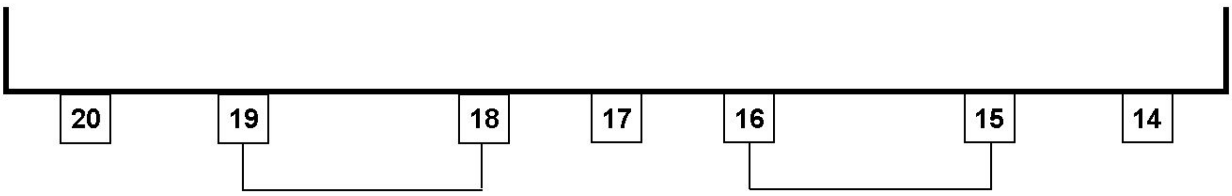


Figure 32. Dispersion of fo and Gain of Super Bass

(d) How to Deal with Pins of Super Bass when not used

Short Pins 15 to 16, Pins 18 to 19 as shown in Figure 33 when the Super Bass function is not used.



Short Pin 15 to 16, Pin 18 to 19

Figure 33. How to Deal with Pins of Super Bass when not used

Ordering Information

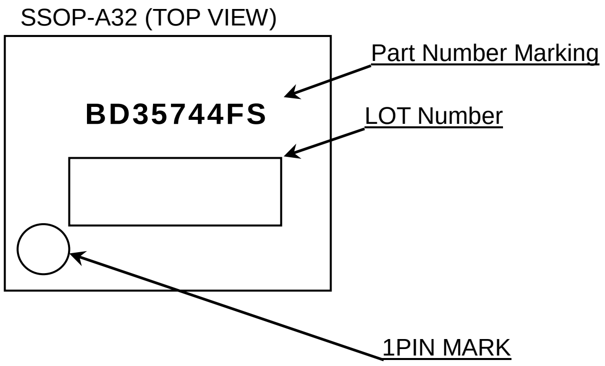
B	D	3	7	5	4	4	F	S	-	E 2

Part Number

Package
FS: SSOP-A32

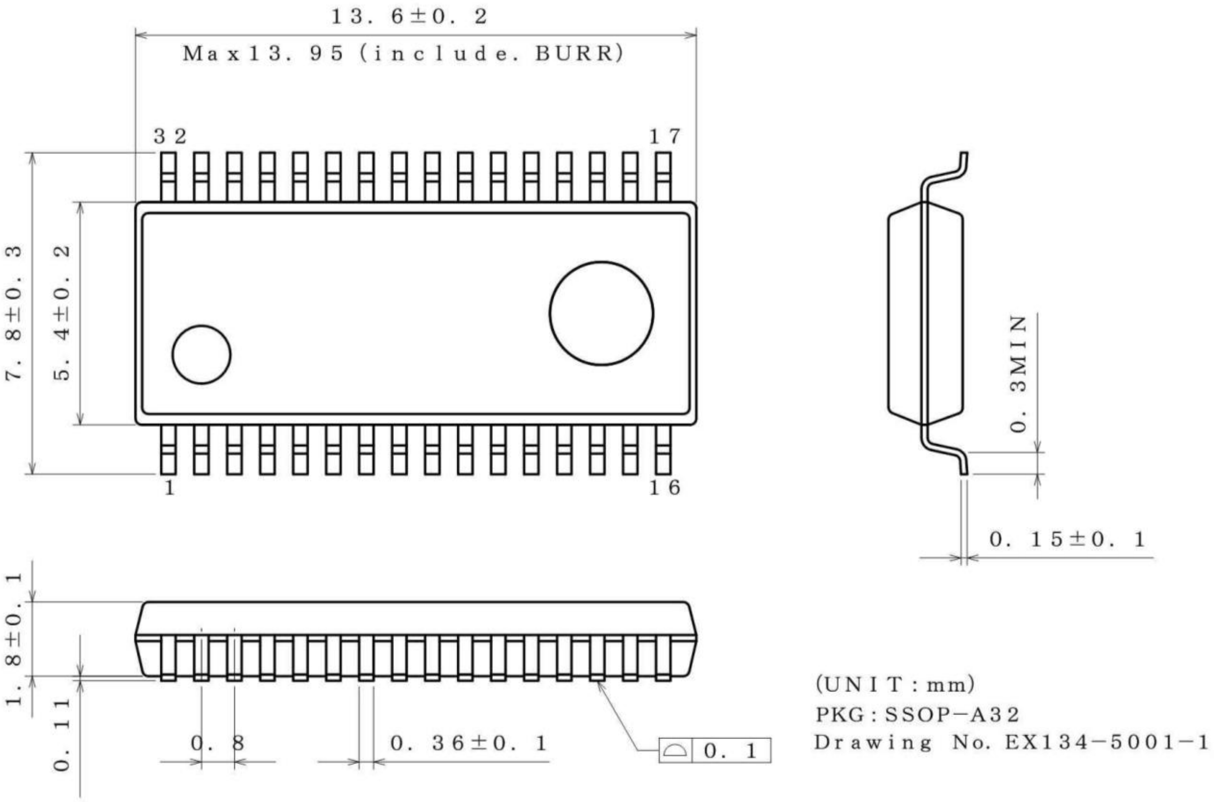
Packaging and forming specification
E2: Embossed tape and reel

Marking Diagram



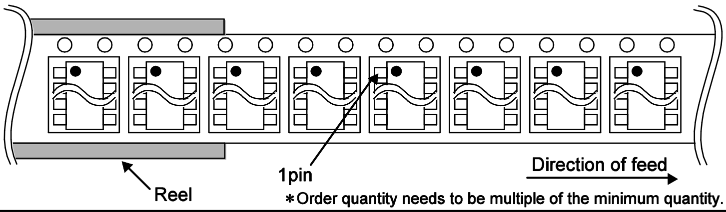
Physical Dimension, Tape and Reel Information

Package Name	SSOP-A32



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

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   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

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2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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   [c] the Products are exposed to direct sunshine or condensation
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2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

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